C-2 Package Outline Drawing

NOTES:
1. PACKAGE, LEADS, COVER MATERIAL: KOVAR™
2. SPACER MATERIAL: ALUMINUM
3. PLATING: ELECTROLYTIC GOLD 50 MICROINCHES MIN., OVER ELECTROLYTIC NICKEL 75 MICROINCHES MIN.
4. ALL DIMENSIONS ARE IN INCHES [MILLIMETERS].
5. TOLERANCES ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED.
6. FIELD REPLACEABLE SMA CONNECTORS.
   TENSOLITE 5602 - 5CCSF OR EQUIVALENT.
   TO MOUNT MODULE TO SYSTEM PLATFORM REPLACE 0-80 HARDWARE WITH DESIRED MOUNTING SCREWS.
C-2B Package Outline Drawing

NOTES:
1. PACKAGE, LEADS, COVER MATERIAL: KOVAR™
2. SPACER MATERIAL: ALUMINUM
3. PLATING: ELECTROLYTIC GOLD 50 MICROINCHES MIN., OVER ELECTROLYTIC NICKEL 75 MICROINCHES MIN.
4. ALL DIMENSIONS ARE IN INCHES [MILLIMETERS].
5. TOLERANCES ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED.
6. FIELD REPLACEABLE SMA CONNECTORS.
   TENSOLITE 5602 - 5CCSF OR EQUIVALENT.
   TO MOUNT MODULE TO SYSTEM PLATFORM REPLACE 0-80 HARDWARE WITH DESIRED MOUNTING SCREWS.